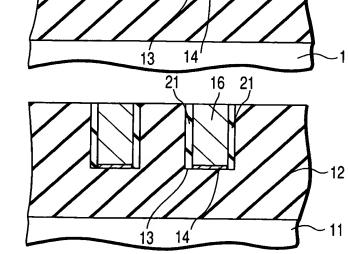
Inventor: Hiroyuki NITTA, et al.
Entitled: "Semiconductor Device Having a
Wiring Layer of Damascene Structure:
Method for Manufacturing the Same"
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16 -15 - 12 -11 13 14

F I G. 1 15a 16 -12 FIG. 3A 13 - 21 -16 - 12 FIG. 3B 13 21 16 21 -12

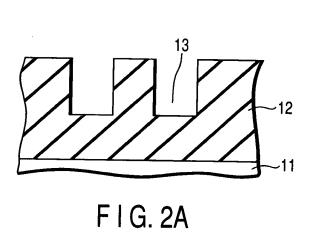


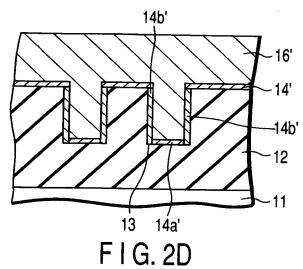
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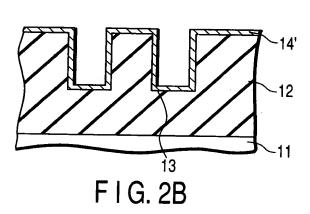


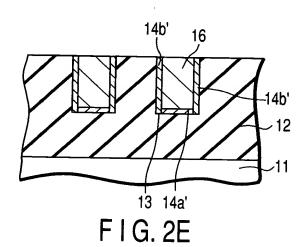
Inventor: Hiroyuki NITTA, et al.
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Method for Manufacturing the Same"

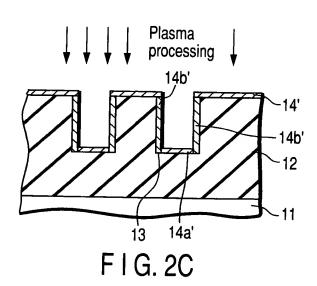
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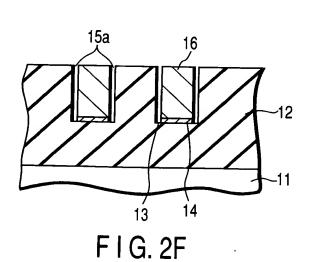










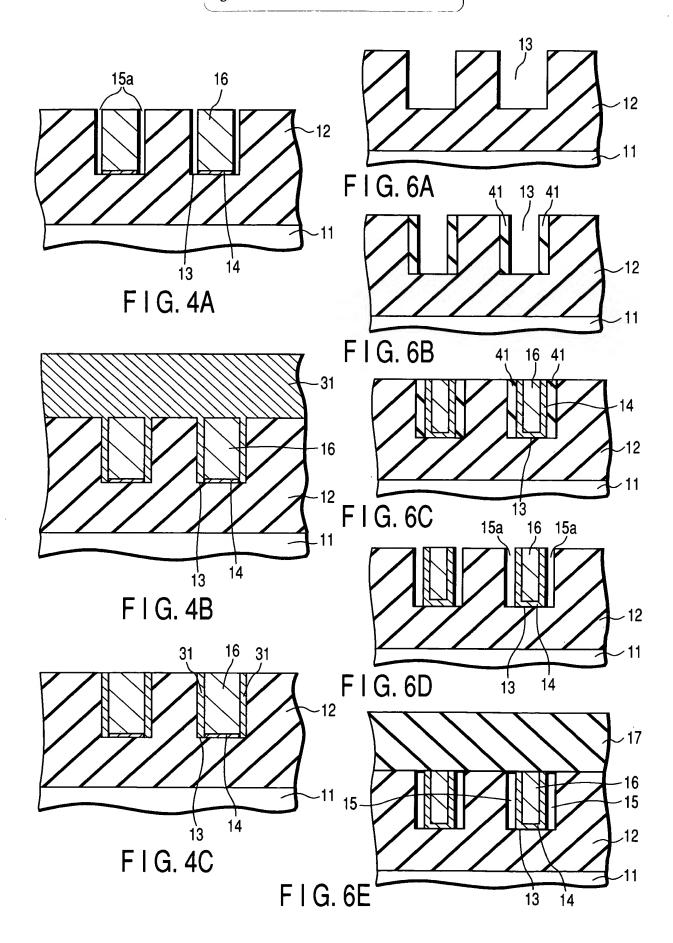




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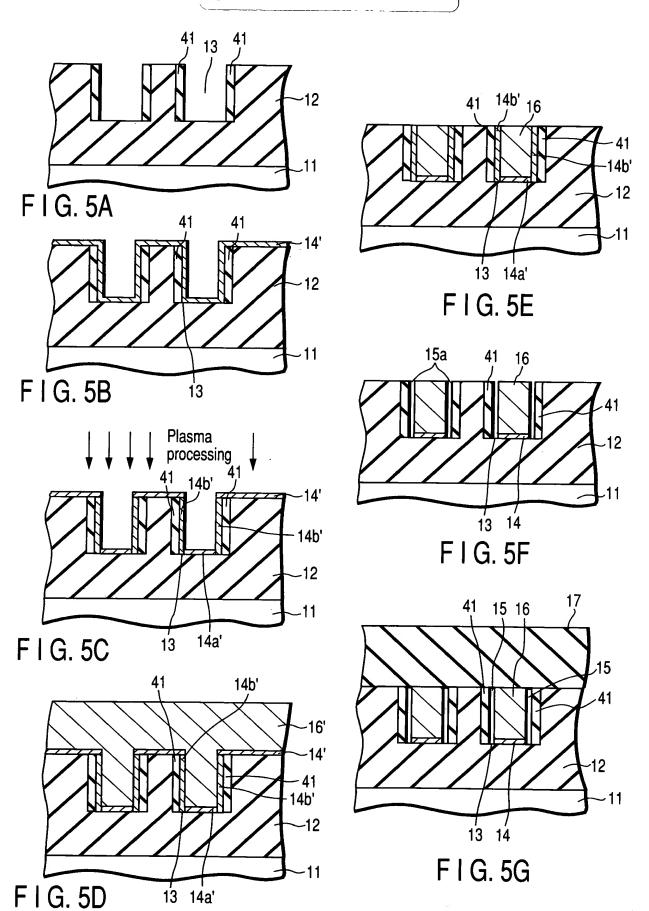




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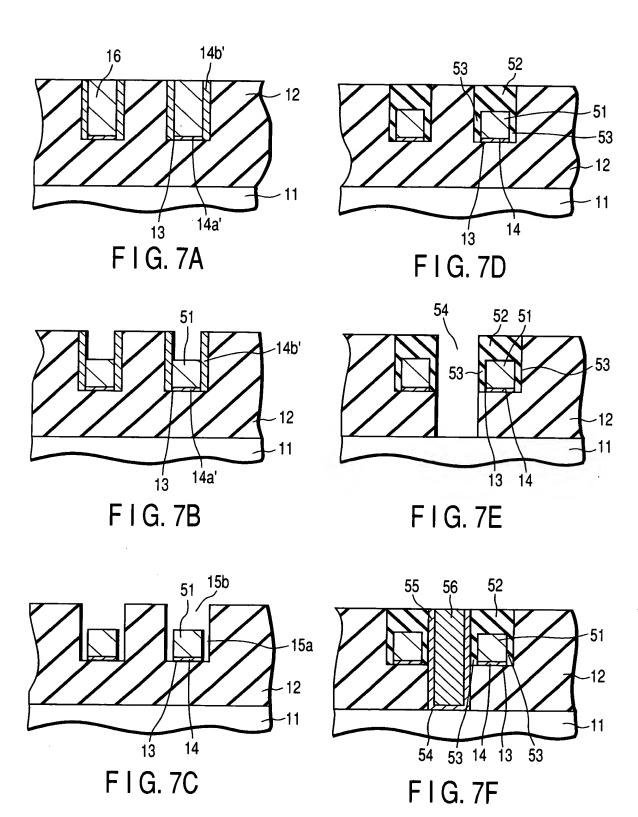
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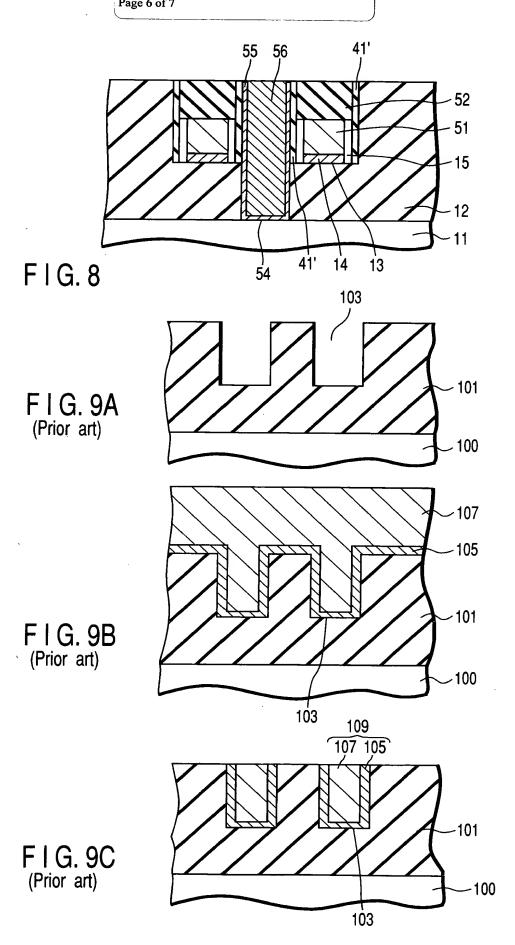


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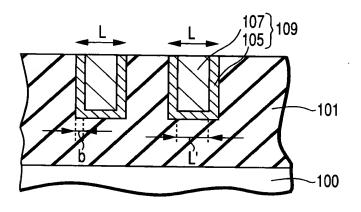


FIG. 10A (Prior art)

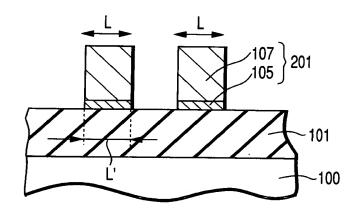


FIG. 10B (Prior art)